

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3001389	substrate or wafer or semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:11
L2	58008	I1 near6 (damage or failure)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:13
L3	52921	holding adj member	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:13
L4	1765845	I3 or head	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:14
L5	109714	I4 same I1	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:37
L6	5120	I5 and I2	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:38
L7	1752	I6 and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:38
L8	94318	sensor near6 (first and second)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:39
L9	70	I7 and I8	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:40
L10	69	I9 and (detect\$3 or sensing)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/09/13 14:41